Win Strong Electronics Co.,Ltd.

DATA SHEET

DESCRIPTION : High Power Infrared LED

Model No: **WS-AS2HPL-850**

REVISION : **1.1**

Material: **Heat resistant polymer / Heat resistant polymer**
Encapsulating Resin / Silicone resin
Lens / Heat resistant clear polymer
Electrodes / Ag plating copper alloy
Die attach / Silver paste
Chip / AlGaAs

Applications:

- **CCD Camera**
- **Night Vision**
- **Infrared applied system**

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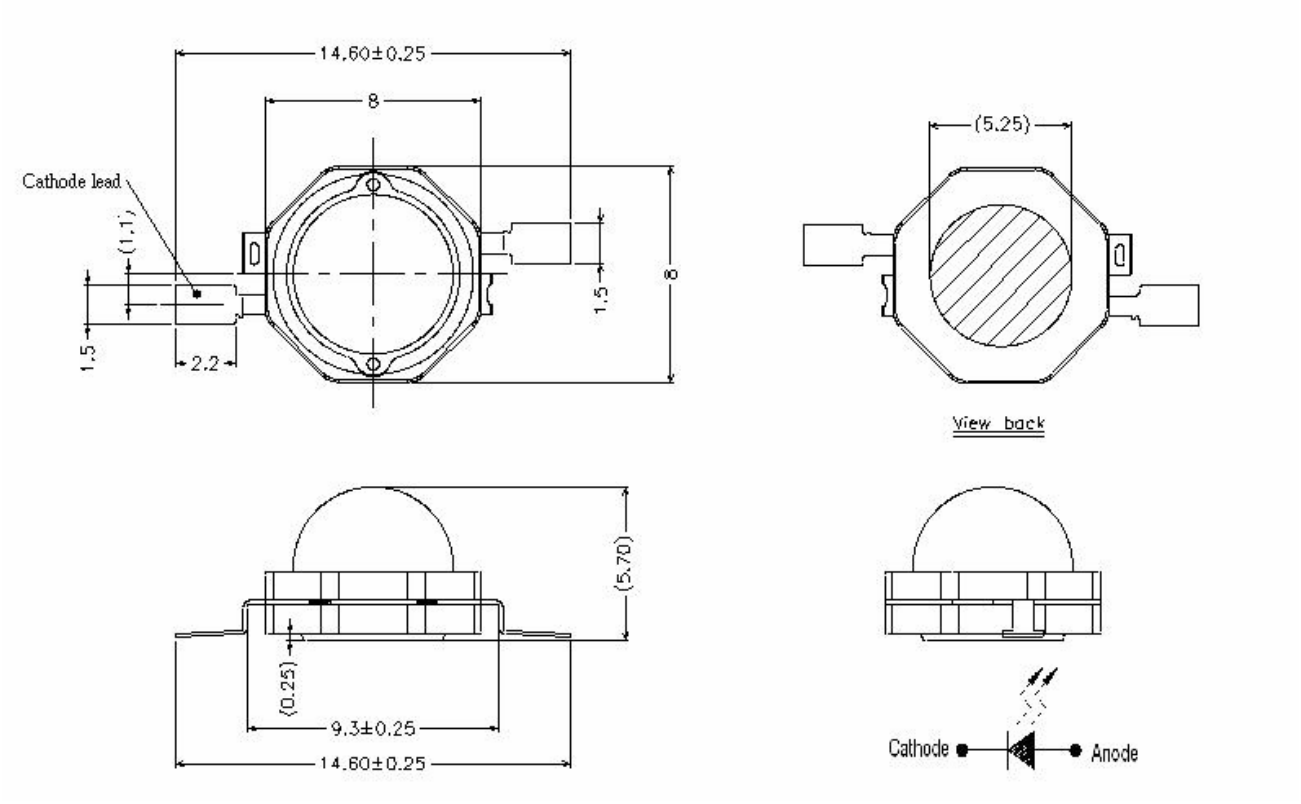
WS-AS2HPL-850

Package Dimensions



Notes: 1.All dimensions are in millimeters
2.Tolerances unless dimensions ±0.25mm

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Absolute Maximum Ratings (Ta=25℃)

Parameter	Symbol	Rating	Units
Forward Current	I_F	700	mA
Reverse Voltage	V_R	5	V
Operating Temperature	T_{opr}	-40 ~ +85	℃
Storage Temperature	T_{stg}	-40 ~ +85	℃
Junction temperature	T_j	125	℃
Power Dissipation @I_F=700mA	P_d	1	W

Note: We suggest that customer should add the heat sink with IR to exclude the heat.

Electro-Optical Characteristics (Ta=25℃)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Units
Total Radiated Power	Po	I_F=350mA	70	120	--	mW
		I_F=700mA	90	240	--	
Radiant Intensity	I_E	I_F=350mA	10	30	--	mW/sr
		I_F=700mA	30	60	--	
Peak Wavelength	λp	I_F=20mA	--	850	--	nm
Spectral Bandwidth	Δλ	I_F=20mA	--	50	--	nm
Forward Voltage	V_F	I_F=350mA	1.0	1.6	2.5	V
		I_F=700mA	1.2	1.9	3.0	
Reverse Current	I_R	V_R=5V	--	--	10	μA
Optical Rise Time	Tr	I_F=20mA	--	11	--	ns
Optical Fall Time	Tf	I_F=20mA	--	7	--	ns
View Angle	2θ 1/2	I_F=20mA	--	140	--	deg
Thermal resistance, junction to heat-sink	Rth j-L	I_F=700mA	--	45	--	℃/W

Note. 1. Radiometric measurement tolerance : ±10%

2 .$2\theta_{1/2}$ is the off axis angle from lamp centerline where the radiant intensity is 1/2 of the peak value.

3. Forward Voltage measurement tolerance : ±0.1V

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Typical Electro-Optical Characteristics Curves

Fig.1 Forward Current vs. Ambient Temperature

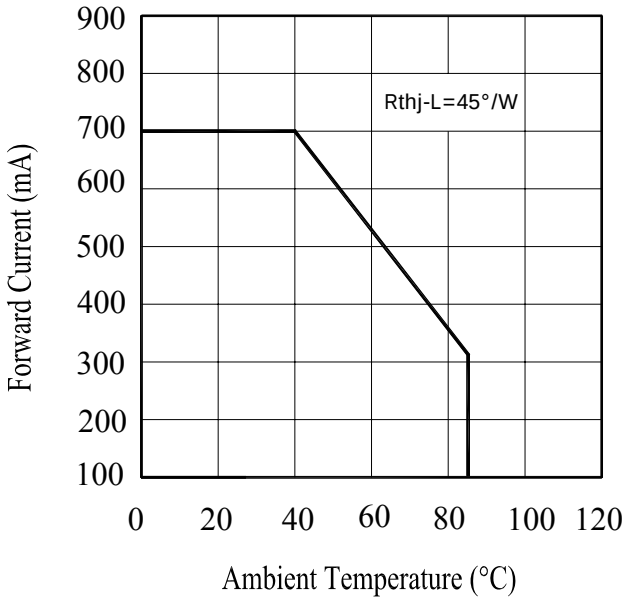


Fig.2 Spectral Distribution

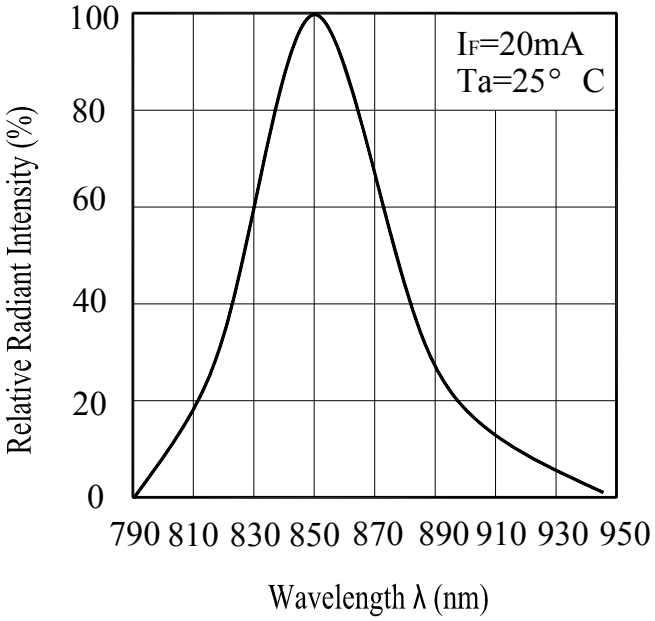


Fig.3 Peak Emission Wavelength Ambient Temperature

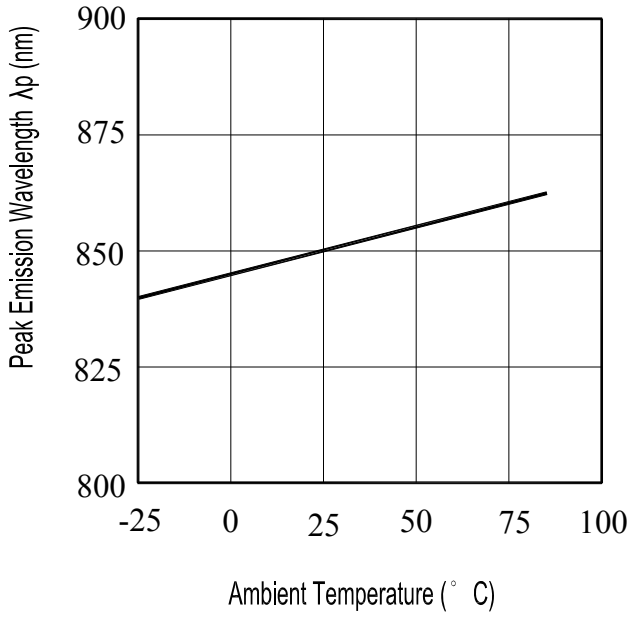
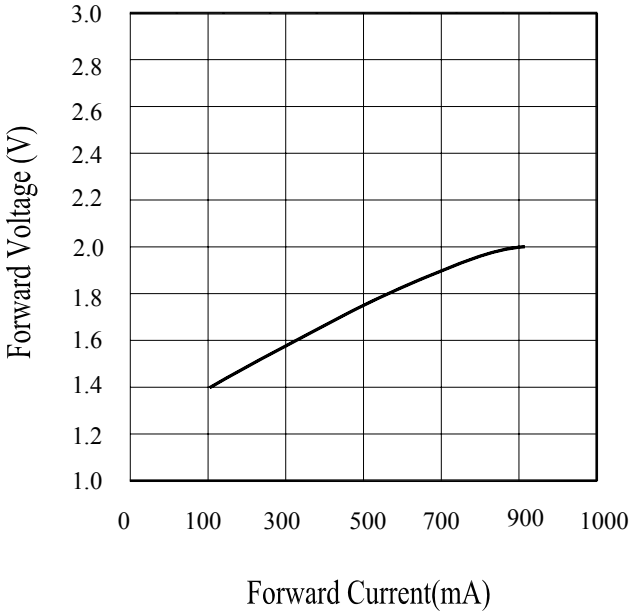


Fig.4 Forward Current vs. Forward Voltage



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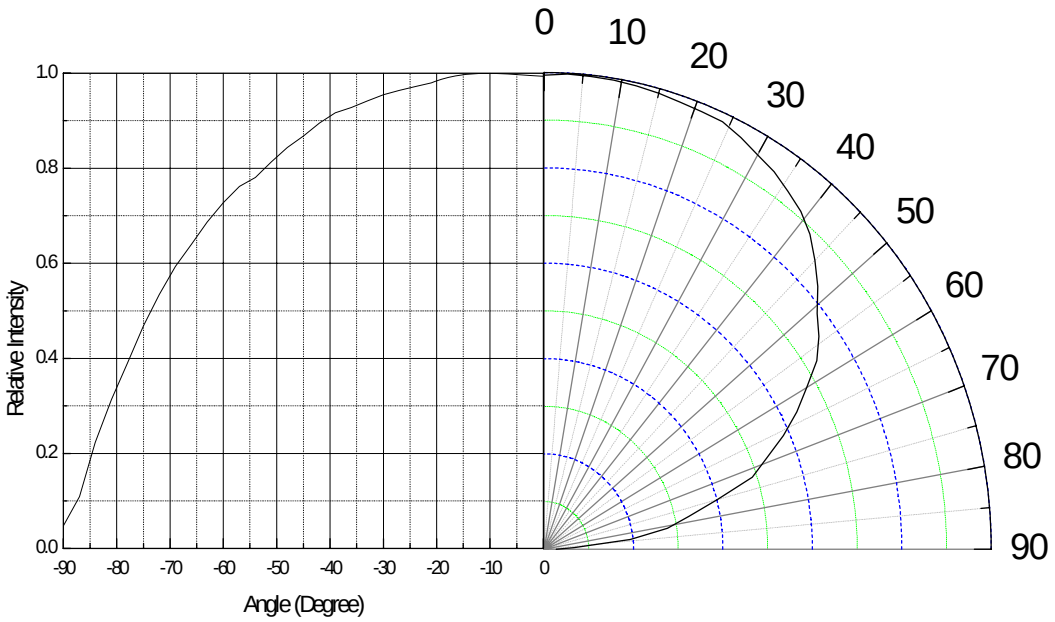
Typical Electro-Optical Characteristics Curves

Fig.5 Relative Radiant Intensity vs. Angular Displacement



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Precautions For Use

1. Over-current-proof

Though HPL-850 has conducted ESD protection mechanism, customer must not use the device in reverse and should apply resistors for extra protection. Otherwise slight voltage shift may cause enormous current change and burn out failure would happen.

2. Thermal Management

1.For maintaining the high flux output and achieving reliability, IR series LED package should be mounted on a metal core printed circuit board (MCPCB) with proper thermal connection to dissipate approximately 1W of thermal energy under 350mA operation.

MCPCB structure

Recommended supplier:
- Kavano Industrial Co., Ltd
- TT Electronics

2.Special thermal designs are also recommended to take in outer heat sink design, such as FR4 PCB on Aluminum with thermal vias or FPC on Aluminum with thermal conductive adhesive, etc.

3.Sufficient thermal management must be conducted, or the die junction temperature will be over the limit under large electronic driving and LED lifetime will decrease critically.

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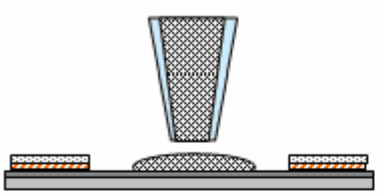
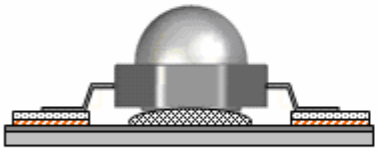
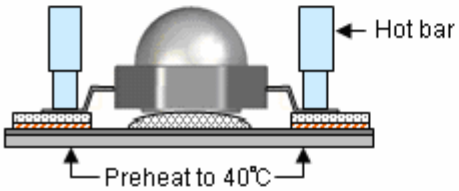
3. Assembly process flow



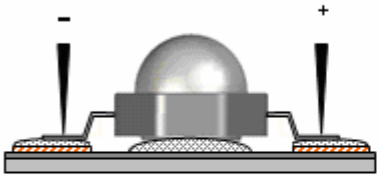
Thermal conductive glue dispensing
Recommended material and its supplier: EpoTek T7109 from Epoxy Technology



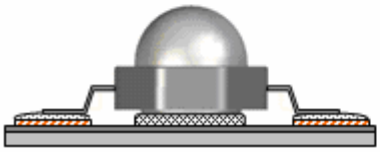
IR-placement **LED emitter**



Hot bar soldering of LED emitter
Note: The MCPCB should be preheated up to 40℃ for increasing the solderability



Functional test of LED emitter



Curing of thermal conductive glue

Handling Indications：Do not handle the IR by the lens at any time during the assembly process. This can cause damage to the optical surfaces or may dislocate the lens if excessive force is applied.

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4. Soldering Iron

1.For prototype builds or small series production runs it is possible to place and solder the LED by hand.

2.Dispensing thermal conductive glue or grease on the substrates and follow its curing spec. Press LED housing to closely connect LED and substrate.

3.It is recommended to hand solder the leads with a solder tip temperature of 280°C for less than 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal.

4.Be careful because the damage of the product is often started at the time of the hand solder.

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